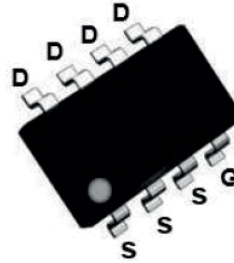
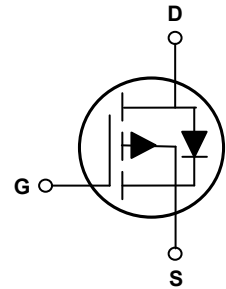


## Main Product Characteristics

$V_{(BR)DSS}$	-40V
$R_{DS(ON)}$	17m $\Omega$ (max.)
$I_D$	-8.8A



SOP-8



Schematic Diagram

## Features and Benefits

- Advanced MOSFET process technology
- Ideal for high efficiency switched mode power supplies
- Low on-resistance with low gate charge
- Fast switching and reverse body recovery



## Description

The GSFQ4017 utilizes the latest techniques to achieve high cell density and low on-resistance. These features make this device extremely efficient and reliable for use in high efficiency switch mode power supplies and a wide variety of other applications.

## Absolute Maximum Ratings ( $T_A=25^\circ\text{C}$ unless otherwise specified)

Parameter	Symbol	Max.	Unit
Drain-Source Voltage	$V_{DS}$	-40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous ( $T_C=25^\circ\text{C}$ ), $V_{GS}=10\text{V}^1$	$I_D$	-8.8	A
Drain Current-Continuous ( $T_C=100^\circ\text{C}$ ), $V_{GS}=10\text{V}^1$		-7.2	A
Drain Current-Pulsed <sup>2</sup>	$I_{DM}$	-35	A
Pulsed Source Current (Body Diode) <sup>2</sup>	$I_{SM}$	-35	A
Maximum Power Dissipation ( $T_C=25^\circ\text{C}$ ) <sup>3</sup>	$P_D$	2.5	W
Single Pulse Avalanche Energy ( $L=0.3\text{mH}$ )	$E_{AS}$	245	mJ
Single Pulse Avalanche Current ( $L=0.3\text{mH}$ )	$I_{AS}$	40	A
Junction-to-Ambient ( $t \leq 10\text{s}$ ) <sup>4</sup>	$R_{\theta JA}$	62	$^\circ\text{C/W}$
Maximum Junction-to-Case	$R_{\theta JC}$	50	$^\circ\text{C/W}$
Operating Junction and Storage Temperature Range	$T_J/T_{STG}$	-55 to +150	$^\circ\text{C}$

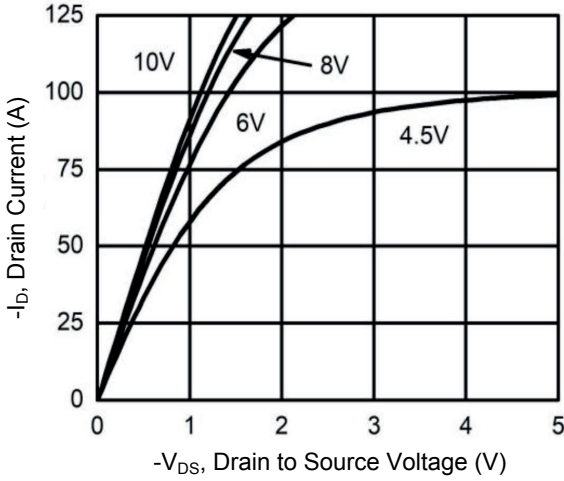
**Electrical Characteristics** ( $T_A=25^\circ\text{C}$  unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Unit
<b>On / Off Characteristics</b>						
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS}=0V, I_D=-250\mu A$	-40	-	-	V
Drain-to-Source Leakage Current	$I_{DSS}$	$V_{DS}=-40V, V_{GS}=0V$	-	-	-1	$\mu A$
Drain-to-Source Leakage Current		$V_{DS}=-40V, V_{GS}=0V, T_J=125^\circ\text{C}$	-	-	-50	$\mu A$
Gate-to-Source Leakage Current	$I_{GSS}$	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	$\pm 100$	nA
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS}=V_{DS}, I_D=-250\mu A$	-1.0	-1.6	-2.9	V
Drain Static-Source On-Resistance	$R_{DS(on)}$	$V_{GS}=-10V, I_D=-8A$	-	12	17	m $\Omega$
		$V_{GS}=-4.5V, I_D=-5A$	-	15	23	m $\Omega$
<b>Dynamic and Switching Characteristics</b>						
Total Gate Charge	$Q_g$	$V_{DD}=-20V, I_D=-8A, V_{GS}=-10V$	-	60	-	nC
Gate-Source Charge	$Q_{gs}$		-	8.8	-	
Gate-Drain Charge	$Q_{gd}$		-	13	-	
Turn-On Delay Time	$t_{d(on)}$	$V_{DD}=-30V, R_G=3\Omega, R_L=1.5\Omega, V_{GS}=-10V, I_D=-8A$	-	8.0	-	nS
Rise Time	$t_r$		-	26.5	-	
Turn-Off Delay Time	$t_{d(off)}$		-	105.2	-	
Fall Time	$t_f$		-	142.1	-	
Input Capacitance	$C_{iss}$	$V_{DS}=-20V, V_{GS}=0V, F=1\text{MHz}$	-	3580	-	pF
Output Capacitance	$C_{oss}$		-	263	-	
Reverse Transfer Capacitance	$C_{rss}$		-	284	-	
Gate Resitance	$R_g$	$F=1\text{MHz}$	-	4.3	-	$\Omega$
<b>Source-Drain Ratings and Characteristics</b>						
Maximum Body-Diode Continuous Current	$I_S$	MOSFET symbol showing the integral reverse p-n junction diode.	-	-8.8	-	A
Maximum Body-Diode Pulse Current	$I_{SM}$		-	-35	-	A
Diode Forward Voltage	$V_{SD}$	$V_{GS}=0V, I_S=-8A, T_J=25^\circ\text{C}$	-	-0.9	-1.3	V
Reverse Recovery Time	$T_{rr}$	$I_F=-8A, di/dt=100A/\mu s, T_J=25^\circ\text{C}$	-	4.5	-	nS
Reverse Recovery Charge	$Q_{rr}$		-	9.5	-	nC

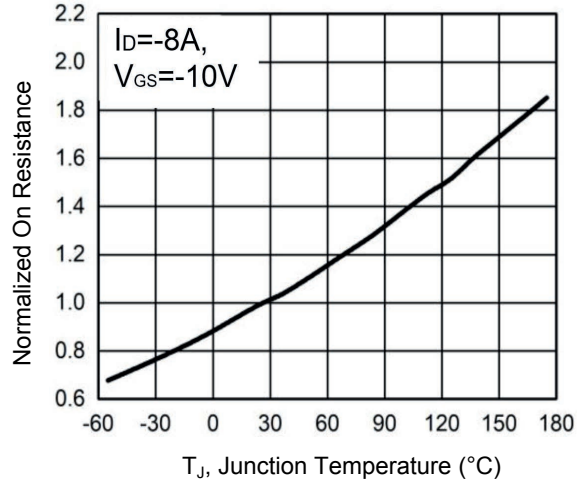
Notes

1. Calculated continuous current based on maximum allowable junction temperature.
2. Repetitive rating; pulse width limited by max. junction temperature.
3. The power dissipation  $P_D$  is based on max. junction temperature, using junction-to-case thermal resistance.
4. The value of  $R_{\theta JA}$  is measured with the device mounted on 1 in<sup>2</sup> FR-4 board with 2oz. Copper, in a still air environment with  $T_A=25^\circ\text{C}$

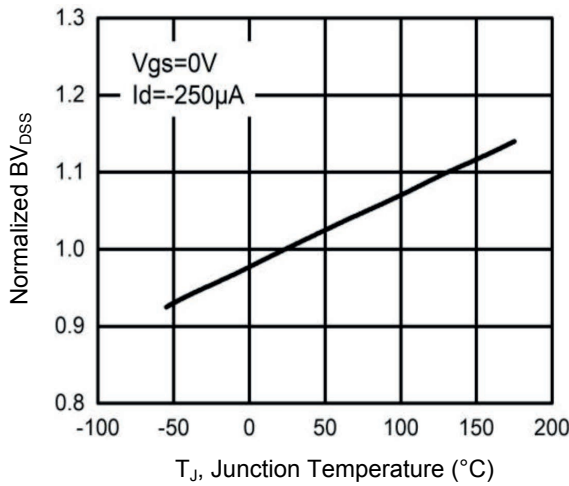
**Typical Electrical and Thermal Characteristic Curves**



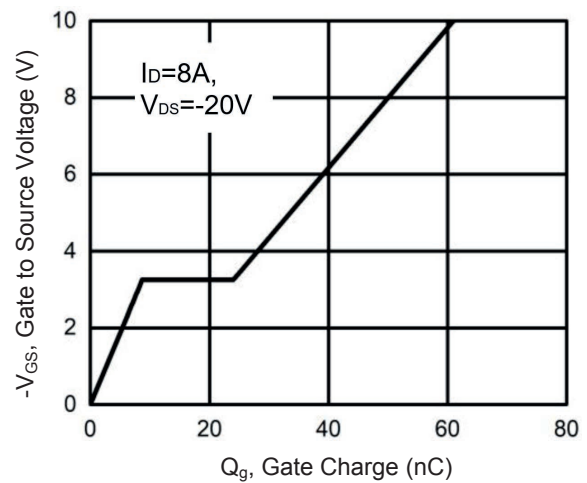
**Figure 1. Output Characteristics**



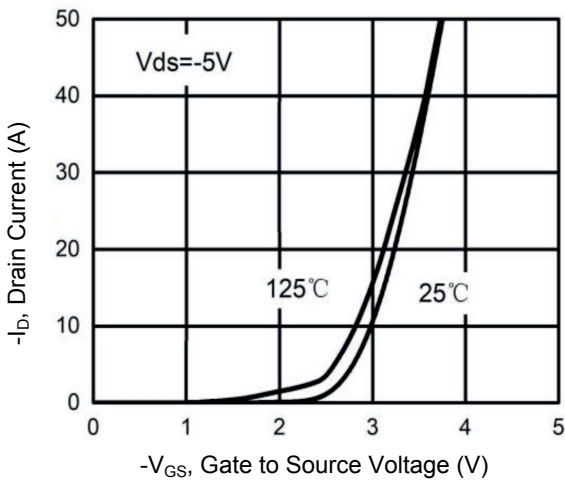
**Figure 2. Normalized  $R_{DS(ON)}$  vs.  $T_J$**



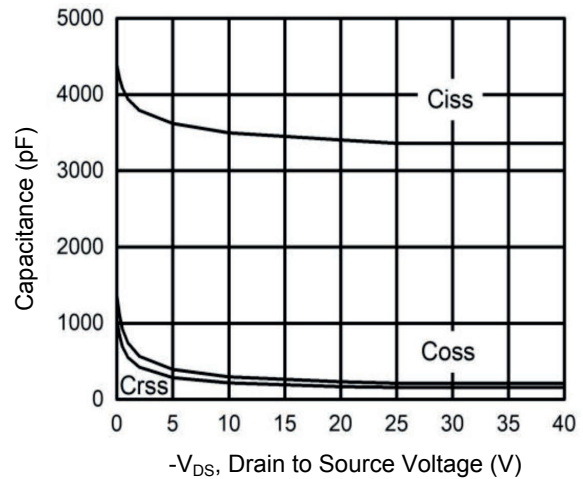
**Figure 3.  $BV_{DS}$  vs.  $T_J$**



**Figure 4. Gate Charge Waveform**

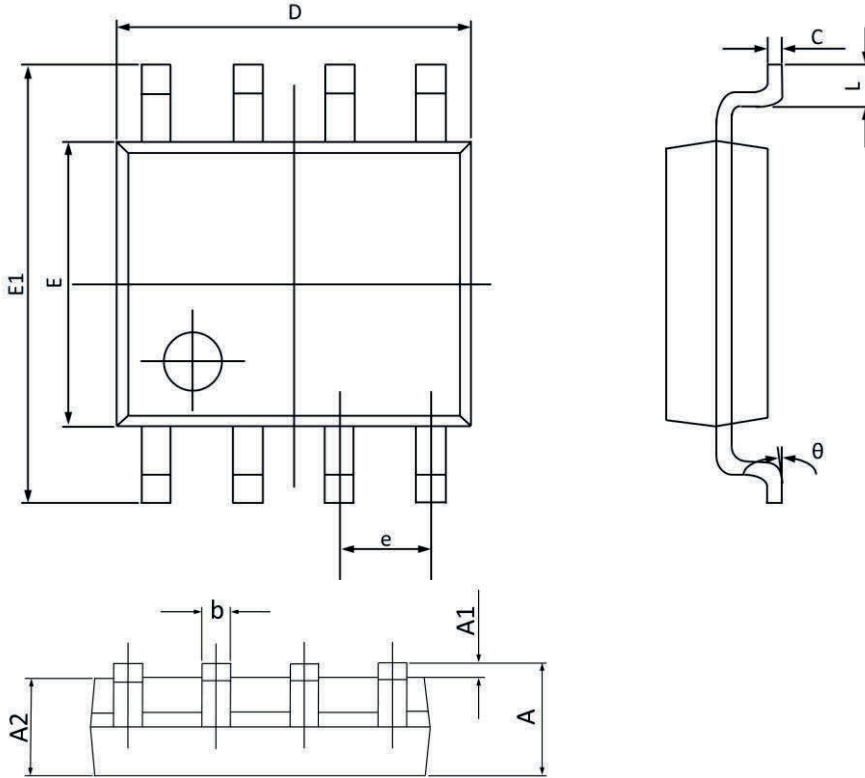


**Figure 5. Transfer Characteristics**



**Figure 6. Capacitance Characteristics**

**Package Outline Dimensions (SOP-8)**



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.300	1.500	0.051	0.059
b	0.350	0.490	0.014	0.019
C	0.190	0.260	0.007	0.010
D	4.700	5.100	0.185	0.201
E	3.700	4.100	0.146	0.161
E1	5.800	6.200	0.228	0.244
e	1.27 BSC		0.05 BSC	
L	0.400	0.900	0.016	0.035
θ	0°	8°	0°	8°

**Order Information**

Device	Package	Marking	Carrier	Quantity
GSFQ4017	SOP-8	Q4017	Tape & Reel	3,000 Pcs / Reel